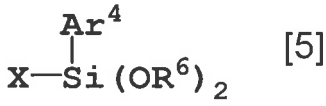
2,2-bis(4-vinylphenyl)propane is preferred, and divinylbenzene is more preferred.

[0058] When the polymerizable composition of the present invention contains the component (b2) as the component (b), its content is 1 to 500 parts by mass with respect to 100 parts by mass of the component (a). Among others, the content is preferably 3 to 250 parts by mass.

[0059] <(b3) Polymerizable alkoxy silicon compound>

The polymerizable alkoxy silicon compound (b3) used in the present invention is a compound of formula [5]:



[5]

In formula [5] described above, X is a phenyl group having at least one substituent having a polymerizable double bond, a naphthyl group having at least one substituent having a polymerizable double bond, a biphenyl group having at least one substituent having a polymerizable double bond, or a phenanthryl group having at least one substituent having a polymerizable double bond, Ar^4 is a condensed ring hydrocarbon group having two or more benzene ring structures (optionally substituted with a C_{1-6} alkyl group), or a hydrocarbon ring assembly group in which two or more aromatic rings are directly bonded through a single bond (optionally substituted with a C_{1-6} alkyl group), and R^6 is methyl group, ethyl group, or isopropyl group.

[0060] Specific examples of X in formula [5] described above include the groups listed as the group X in formula [1] in the alkoxy silicon compound A of formula [1] and can particularly include the groups listed as preferred groups of the group X in formula [1].

Specific examples of Ar^4 in formula [5] described above include the groups listed as the group Ar^1 in formula [1] and can particularly include the groups listed as preferred groups of the group Ar^1 in formula [4].

Specific examples of the compound of formula [5] include the compounds listed as specific examples of the alkoxy silicon compound A of formula [1].